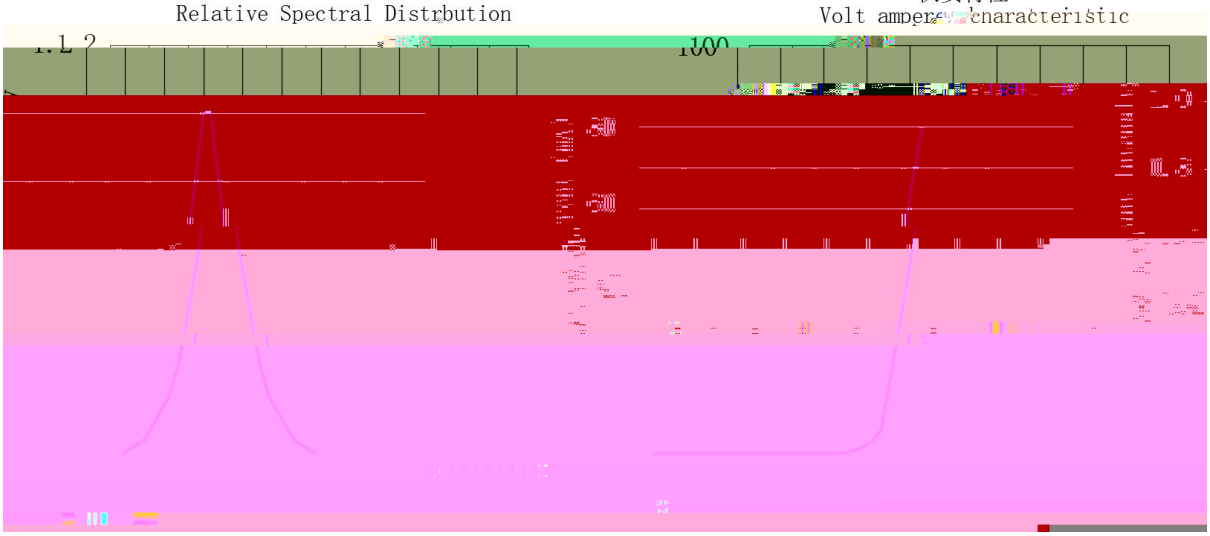
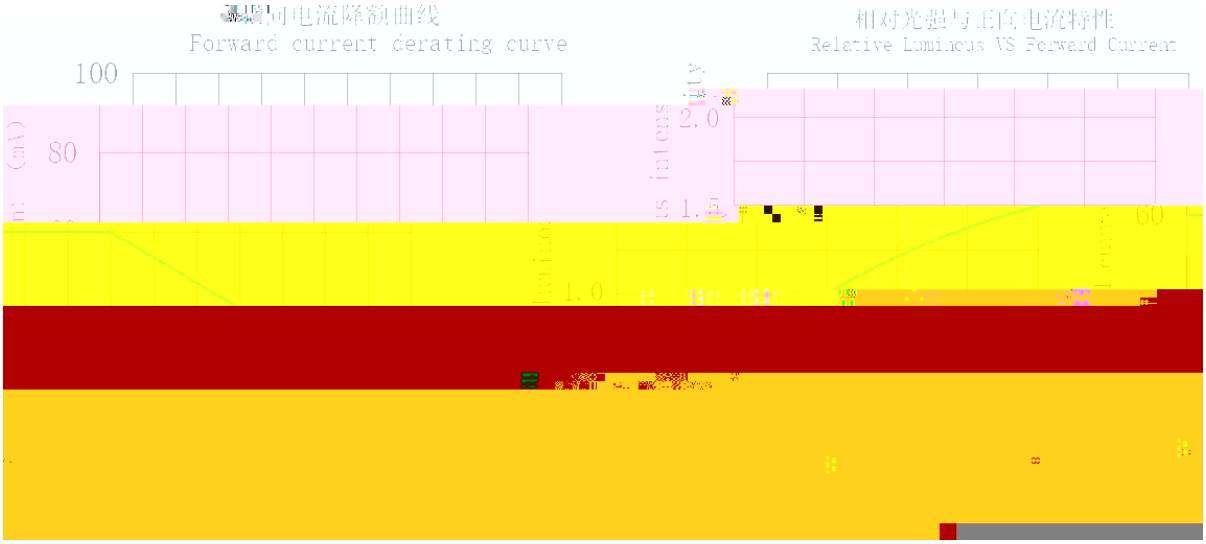
典型特性曲线

Typical Characteristics Curves

光谱分布曲线
Relative Spectral Distribution

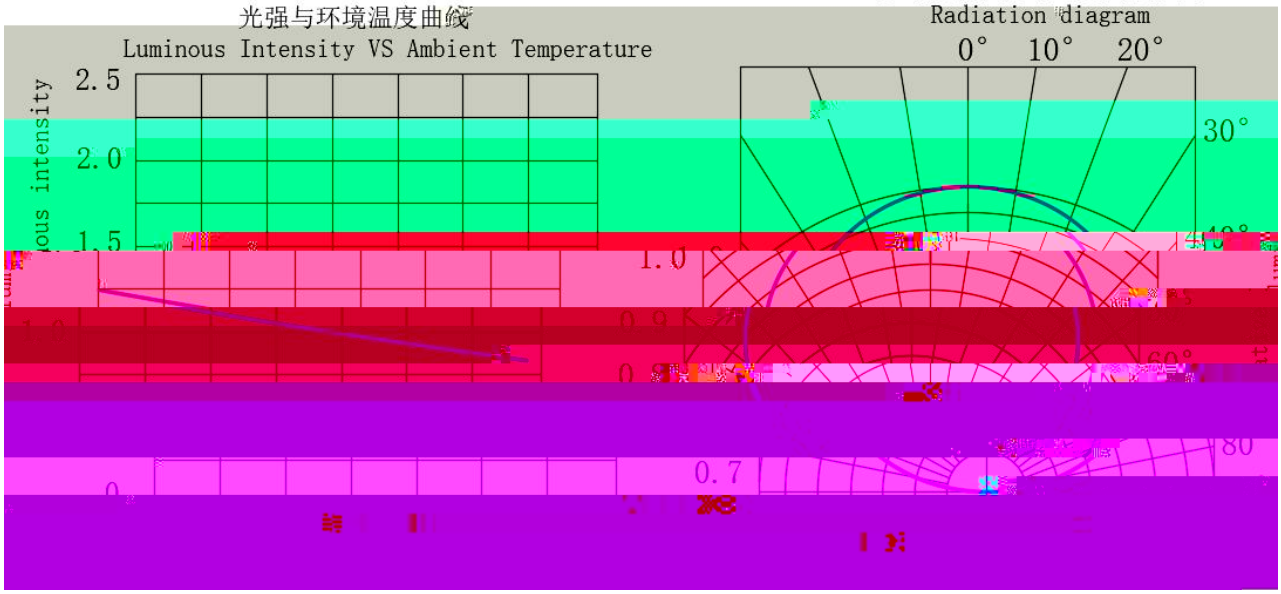


伏安特性
Volt ampere characteristic



相对光强与正向电流特性
Relative Luminous VS Forward Current

光强与环境温度曲线
Luminous Intensity VS Ambient Temperature



相对辐射强度与空间角度关系
Radiation diagram

25 ± 5 /Note If not otherwise indicated the test environment temp erature is 25 ± 5

可靠性试验

Reliability Test Items And Conditions

Class	Test item	Testing environment	Testing time	Reference standard
Endurance test	Working life	Continuous lighting at the maximum rated current at room	1000 hours +72 -24hours	MIL-STD-750D:1026 MIL-STD-883D:1005 JIS C 7021:B-1
	High temperature and high humidity	IR-Reflow In-Board, 2 Times Ta= 85±5 , RH= 90 95%	240hours) ± 2hours)	MIL-STD-202F:103B JIS C 7021:B-11
	High-temperature storage	Ta= 85±5	1000 hours -24 +72) -24hours+72hours	MIL-STD-883D:1008 JIS C 7021:B-10
	Low temperature	Ta= -40±5		JIS C 7021:B-12
	Cold and hot cycle	105 25 -55 25 30mins 5mins 30mins 5mins	100 100 Circles	MIL-STD-202F:107D MIL-STD-750D:1051 MIL-STD-883D:1010
	Hot and cold impact	IR-Reflow In-Board, 2 Times 100± 5 -40 ± 5 20mins 20mins	100 100 Circles	MIL-STD-202F:107D MIL-STD-750D:1051 MIL-STD-883D:1011
	Anti-tin test	T.sol= 260 ± 5	10 ± 1secs 2 2times	MIL-STD-202F:210A MIL-STD-750D:2031
	Infrared reflowwelding There is lead process	heat up speed(183) 3 / keep temperature 125(±25) 120 keep temperature 183 60-150 maximum temperature 235 +5/-0 keep235 +5/-0 10-15 cooling rate	--------	MIL-STD-750D:2031.2 J-STD-020C
	Infrared reflow welding Lead-free process	heat up speed(217) 3 / keep temperature 175(±25) 180 keep temperature 217 60-120 maximum temperature 255 +0/-5 keep255 +0/-5 5-10 cooling rate 6	--------	MIL-STD-750D:2031.2 J-STD-020C
	Weldability test	Soldering temperature T.sol= 235 ± 5 Immersion speed 25±2.5 mm/ 95% Tin loading rate ≥ 95% pad area Immersion time: 2 ± 0.5 seconds	Immersion	

外形尺寸

Outline Dimension

1. γ ٩ β شخ mm

Remarks: All dimensions are in millimeters.

2. ≠ `E `E شخ ±0.25mm

Tolerance is ±0.25mm unless otherwise noted